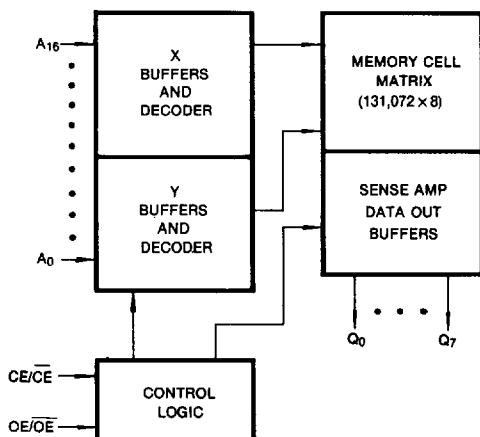


KM23C1000/1010(G/J)**CMOS MASK ROM****1M-Bit (128K × 8) CMOS MASK ROM****FEATURES**

- 131,072 × 8 bit organization
- Fast access time : 120ns(max.)
- Supply voltage : single +5V
- Current consumption
Operating : 30 mA(max.)
Standby : 50 μ A(max.)
- Fully static operation
- All inputs and outputs TTL compatible
- Three state outputs
- Polarity programmable chip enable and output enable pin
- Package : 28-pin, 600mil, plastic DIP
32-pin, 600mil, plastic DIP (JEDEC standard)
32-pin, 525mil, plastic SOP
32-pin, PLCC

FUNCTIONAL BLOCK DIAGRAM

Pin Name	Pin Function
A ₀ -A ₁₆	Address Inputs
Q ₀ -Q ₇	Data Outputs
CE/CE*	Chip Enable
OE/OE*	Output Enable
V _{CC}	Power (+5V)
V _{SS}	Ground
NC	No Connection

* User Selectable Polarity

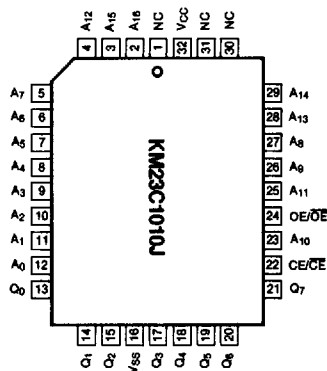
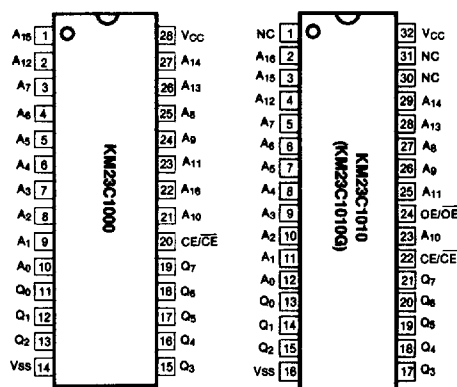
GENERAL DESCRIPTION

The KM23C1000/1010 is a fully static mask programmable ROM organized 131,072 × 8 bit. It is fabricated using silicon-gate CMOS process technology.

This device operates with a 5V single power supply, and all inputs and outputs are TTL compatible. Because of its asynchronous operation, it requires no external clock assuring extremely easy operation.

It is suitable for use in program memory of micro-processor, and data memory, character generator.

The KM23C1000 is packaged in a 28-DIP, the KM23C1010 in a 32-DIP, the KM23C1010G in a 32-SOP, and the KM23C1010J in a 32-PLCC, provides polarity programmable CE and OE buffer as user option mode.

PIN CONFIGURATION

KM23C1000/1010(G/J)**CMOS MASK ROM****ABSOLUTE MAXIMUM RATINGS**

Item	Symbol	Rating	Unit
Voltage on Any Pin Relative to V_{SS}	V_{IN}	-0.3 to +7.0	V
Temperature Under Bias	T_{bias}	-10 to +85	°C
Storage Temperature	T_{stg}	-55 to +150	°C

* Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltage reference to V_{SS} , $T_A = 0$ to 70°C)

Item	Symbol	Min	Typ	Max	Unit
Supply Voltage	V_{CC}	4.5	5.0	5.5	V
Supply Voltage	V_{SS}	0	0	0	V

DC CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min	Max	Unit
Operating Current	I_{CC}	$\overline{CE} = \overline{OE} = V_{IL}$, $f = 5.0\text{MHz}$ all output open	—	30	mA
Standby Current (TTL)	I_{SB1}	$\overline{CE} = V_{IH}$, all output open	—	1	mA
Standby Current (CMOS)	I_{SB2}	$\overline{CE} = V_{CC}$, all output open	—	100	μA
Input Leakage Current	I_{LI}	$V_{IN} = 0$ to V_{CC}	—	10	μA
Output Leakage Current	I_{LO}	$V_{OUT} = 0$ to V_{CC}	—	10	μA
Input High Voltage, All Inputs	V_{IH}		2.2	$V_{CC} + 0.3$	V
Input Low Voltage, All Inputs	V_{IL}		-0.3	0.8	V
Output High Voltage Level	V_{OH}	$I_{OH} = -400\mu\text{A}$	2.4	—	V
Output Low Voltage Level	V_{OL}	$I_{OL} = 2.1\text{mA}$	—	0.4	V

CAPACITANCE ($T_A = 25^\circ\text{C}$, $f = 1.0\text{MHz}$)

Parameter	Symbol	Test Conditions	Min	Max	Unit
Output Capacitance	C_{OUT}	$V_{OUT} = 0\text{V}$	—	8.0	pF
Input Capacitance	C_{IN}	$V_{IN} = 0\text{V}$	—	8.0	pF

Note: Capacitance is periodically sampled and not 100% tested.

MODE SELECTION (KM23C1000)

$CE/\overline{CE}$	Mode	Data	Power
L/H	Standby	High-Z	Standby
H/L	Operating	D_{OUT}	Active

KM23C1000/1010(G/J)**CMOS MASK ROM****MODE SELECTION (KM23C1010)**

CE/ $\overline{\text{CE}}$	OE/ $\overline{\text{OE}}$	Mode	Data	Power
L/H	X	Standby	High-Z	Standby
H/L	L/H	Operating	High-Z	Active
	H/L	Operating	D _{OUT}	Active

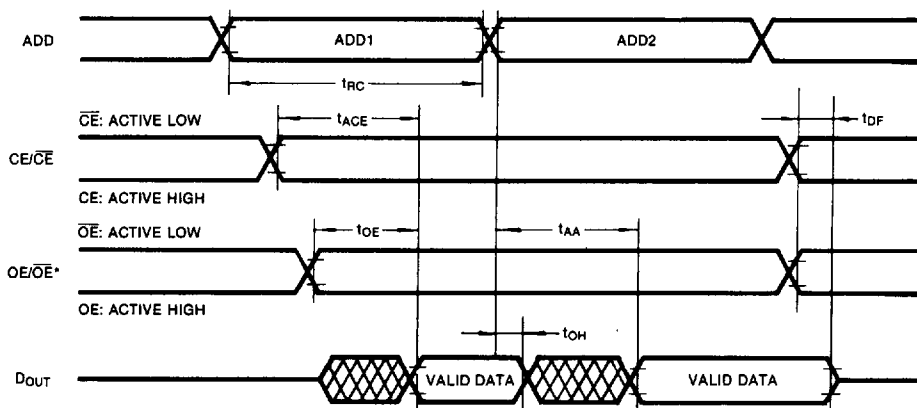
AC CHARACTERISTICS

TEST CONDITIONS ($T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted.)

Item	Value
Input Pulse Levels	0.6V to 2.4V
Input Rise and Fall Times	10ns
Input and Output Timing Levels	0.8V and 2.0V
Output Loads	1 TTL Gate and $C_L = 100\text{pF}$

READ CYCLE

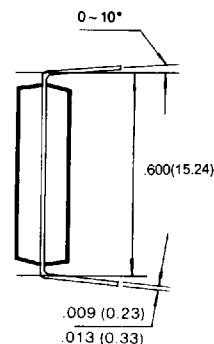
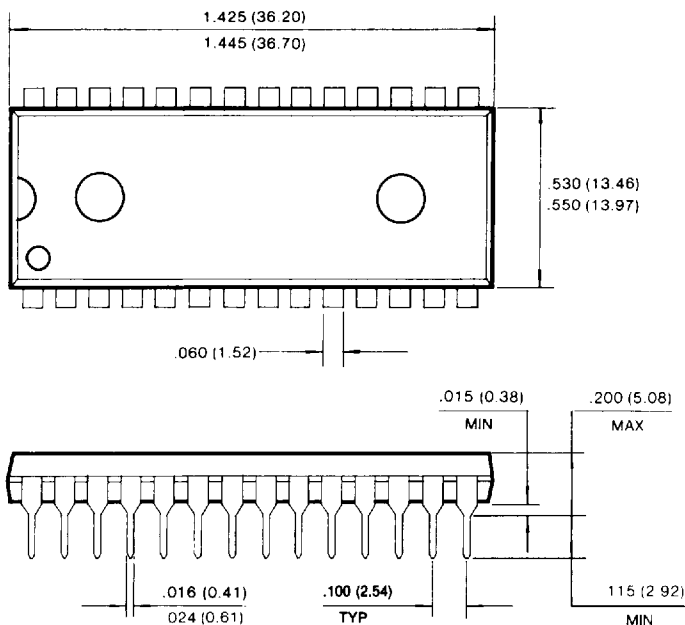
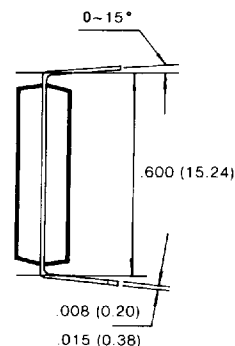
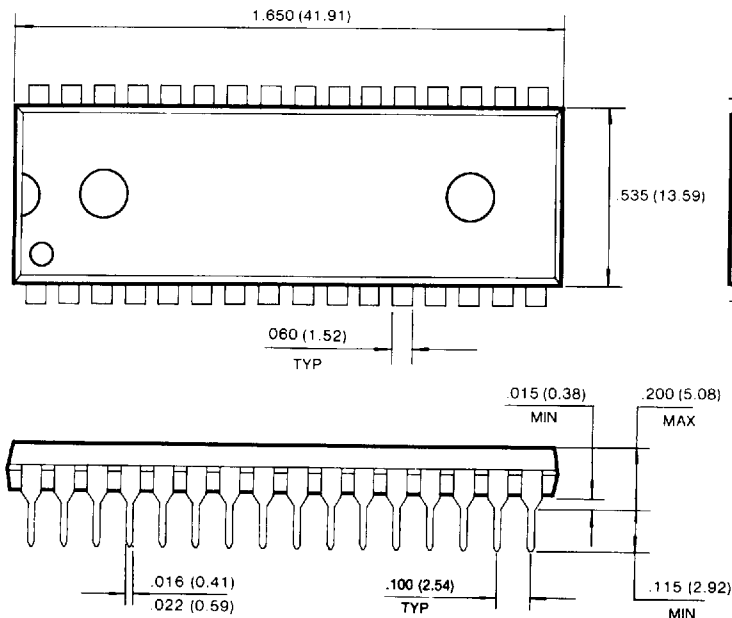
Parameter	Symbol	KM23C 1000-12 KM23C1010(G/J)-12		KM23C 1000-15 KM23C1010(G/J)-15		KM23C 1000-20 KM23C 1010(G/J)-20		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	t_{RC}	120		150		200		ns
Chip Enable Access Time	t_{ACE}		120		150		200	ns
Address Access Time	t_{AA}		120		150		200	ns
Output Enable Access Time	t_{OE}		60		70		90	ns
Output or Chip Disable to Output High-Z	t_{DF}		20		30		40	ns
Output Hold from Address Change	t_{OH}	0		0		0		ns

TIMING DIAGRAM**READ**

* The KM23C1000 is not available.

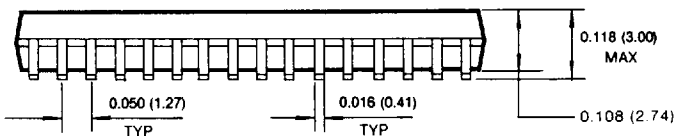
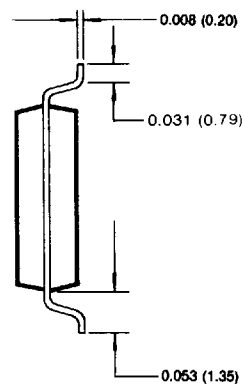
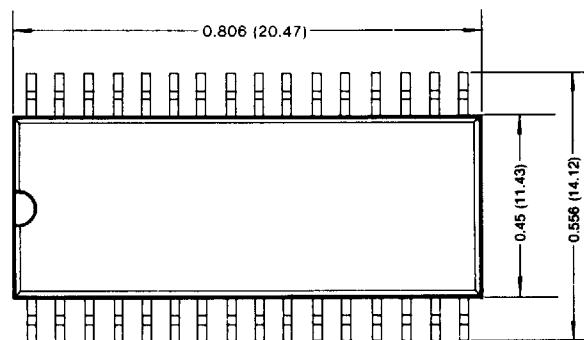
KM23C1000/1010(G/J)**CMOS MASK ROM****PACKAGE DIMENSIONS****28 LEAD PLASTIC DUAL IN LINE PACKAGE (KM23C1000)**

Units: Inches (millimeters)

**32 LEAD PLASTIC DUAL IN LINE PACKAGE (KM23C1010)**

KM23C1000/1010(G/J)**CMOS MASK ROM****PACKAGE DIMENSIONS (Continued)****32 LEAD SMALL OUTLINE PACKAGE (KM23C1010G)**

Units: Inches (millimeters)



KM23C1000/1010(G/J)**CMOS MASK ROM****PACKAGE DIMENSIONS****32 PIN PLASTIC LEADED CHIP CARRIER (KM23C1010J)**

Units: Inches (millimeters)

